

ABSTRACT

Device for dispensing and distributing flux-free solder on a substrate

A device (1) for dispensing and distributing flux-free solder on a substrate (2) comprises an elongated tool (7), a tool mount (9), an ultrasonic generator (10), a wire guide tube (11), and optionally a heat sink (14) and a housing (15). The tool (7) can be fixed to the tool mount (9) and has a longitudinal borehole which opens into an opening on the tip (8) of the tool (7). The wire guide tube (11) extends along a central longitudinal axis through the ultrasonic generator (10) and the tool mount (9), protrudes into the longitudinal borehole of the tool (7) and reaches up to a position above the tip (8) of the tool (7). The wire guide tube (11) does not touch the tool (7). The ultrasonic generator (10) is fixed to the tool mount (9). Advantageously, a cooling chamber (20) which can actively be cooled is formed between an inner wall of the housing (15) and the ultrasonic generator (10).

(Fig. 1)